

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KUNIYUKI OHTSUKA	08/28/2015
RECEIVING PARTY DATA	
Name:	HONDA MOTOR CO., LTD.
Street Address:	1-1, MINAMI-AOYAMA 2-CHOME
Internal Address:	MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	107-8556
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14772446
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Address Line 4:	WILLOUGHBY, OHIO 44094
ATTORNEY DOCKET NUMBER:	KOY-40056
NAME OF SUBMITTER:	DAVID E. SPAW
SIGNATURE:	/David E. Spaw/
DATE SIGNED:	09/04/2015
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, new and useful improvements have been made by the undersigned in

BLOW-MOLDING MOLD

that are the subject of an application for a U.S. Patent, (Application No. 14/772446, filed 09/03/2015), which application is further identified as Rankin, Hill & Clark LLP Docket No. KOY-40056.

WHEREAS, HONDA MOTOR CO., LTD., a corporation of Japan, and having a place of business at 1-1, Minami-Aoyama 2-chome, Minato-ku, Tokyo, 107-8556, Japan, hereinafter referred to as "assignee", is desirous of acquiring all right, title, and interest throughout the world in, to, and under said improvements and inventions and patent rights therefor.

NOW, THEREFORE, be it known that, for valuable consideration, the receipt and sufficiency of which are hereby acknowledged, all right, title, and interest, in the United States and throughout the world, in, to and under said improvements and inventions and all patents, patent applications, patent rights, and inventor's certificates thereof, therefor, and therein, including without limitation said application for patent in the United States, all divisions and continuations thereof, all patents which may be granted thereon, all reissues and extensions thereof, all right to sue for past infringement thereunder, all patents which may be granted for said improvements and inventions by states or nations other than the United States, or by other authority, entity, or organization, and all applications therefor, have been and are hereby sold, assigned, transferred, and delivered unto assignee, its successors and assigns; and it is covenanted and agreed by the undersigned, and for executors, administrators, and legal representatives of the undersigned, that at assignee's request any and all applications, affidavits, assignments, and other instruments will be made, executed, and delivered as may be necessary, or desirable to secure for or vest in assignee, its successors or assigns, any improvement, inventions, right, title, interest, application, patent, patent right or other right or property covered by this assignment, and the United States Commissioner of Patents and Trademarks is hereby requested and authorized to issue any and all United States patents granted on any of said applications to assignee as owner of the entire right, title, and interest in, to, and under the same, and appropriately empowered officials of foreign countries are hereby authorized to issue any letters patent granted on any of said applications to assignee as owner of the entire right, title and interest in, to, and under the same.

The undersigned hereby grants the firm of Rankin, Hill & Clark LLP the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

IN WITNESS WHEREOF, this assignment has been executed below by the undersigned:

(1) Inventor Name (sole): Kuniyuki Ohtsuka

Signature: Kuniyuki Ohtsuka

Today's Date: 28 Aug. 2015

Witness: _____

Witness: _____